



Keetata™

東莞健達照明有限公司
DONGGUAN KEE TAT LIGHTING LTD.

SPECIFICATION FOR KEE TAT LED LAMP

KEETAT Document No. : SPC/KT-5JWNC7GG0-518

KEETAT Model No. : KT-5JWNC7GG0-518

Customer Part No.:

Sample No. : KT-WN4473

Rev. No. : 02

Date: 2011-09-16


Description:

5mm Straw hat LED Lamp in Long-lead White Color with Water
Transparent Lens

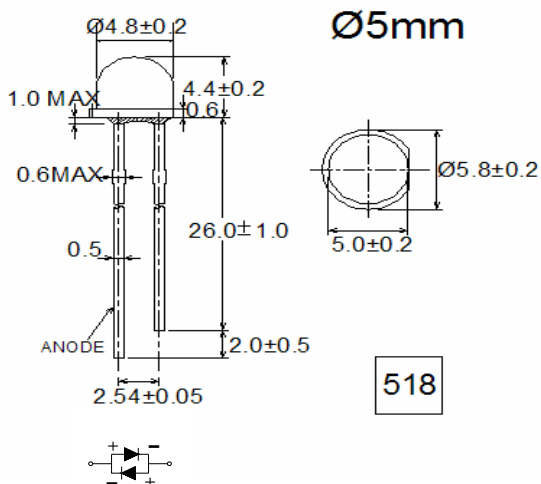

Dice Material: InGaN

Formal Specification



Approved By Customer	Confirmed By KEETAT
	



Package Outline	Features
	High Luminous Intensity Output White Color LED Lamp
	Chip Technology-- InGaN
	Standard 5mm Water Clear Packages
	Viewing Angle 160 Degree (Reference)
	Picture 

Absolute Maximum Ratings at Ta = 25°C

Parameter	Symbol	Absolute maximum Rating	Unit
Forward Current	I_F	20	mA
Peak Forward Current*	I_{FP}	100	mA
Reverse Voltage	V_R	5	V
Power Dissipation	P_D	72	mW
Operation Temperature	T_{opr}	-30 ~ +80	°C
Storage Temperature	T_{stg}	-40 ~ +100	°C
Lead Soldering Temperature	T_{sol}	260°C for 5sec Max	

* Where pulse width ≤ 0.1 msec, duty cycle $\leq 1/10$

Typical Electrical & Optical Characteristics at Ta = 25°C

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Luminous Intensity	I_v	$I_F = 20$ mA	550	850	1250	mcd
Forward Voltage	V_F	$I_F = 20$ mA	2.8	3.2	3.6	V
Chromaticity Coordinates	x	$I_F = 20$ mA	---	0.31	---	---
	y	$I_F = 20$ mA	---	0.31	---	---
Reverse Current	I_R	$V_R = 5$ V	---	---	10	μ A
50% Power Angle	$2\theta_{1/2}$	$I_F = 20$ mA	---	160	---	deg

Luminous Intensity Bin Table ($I_F = 20$ mA):

Rank Name	Min (mcd)	Max (mcd)
1	550	1250

*Tolerance for each bin limit is $\pm 15\%$

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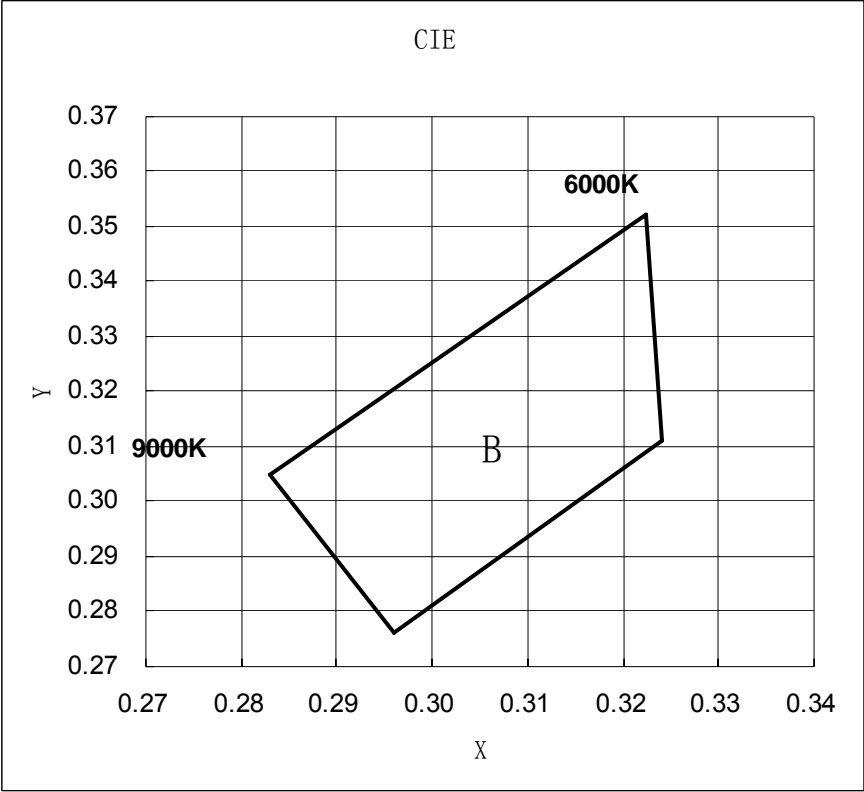


Forward Voltage Bin Table (IF = 20mA):

Rank Name	Min (V)	Max (V)
1	2.8	3.6

*Tolerance for each bin limit is $\pm 0.1V$

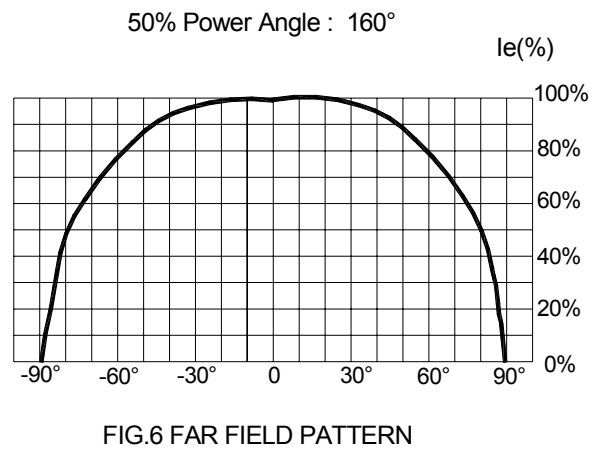
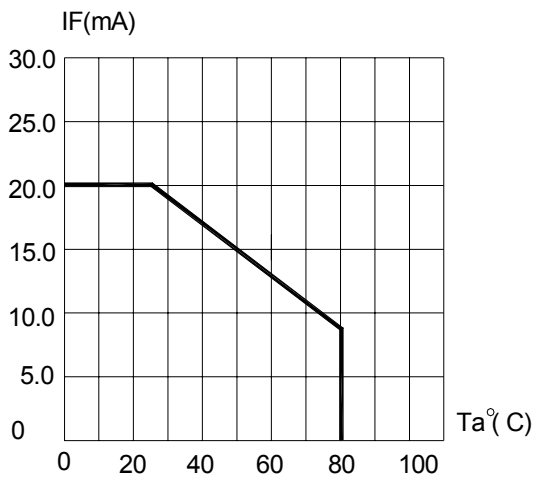
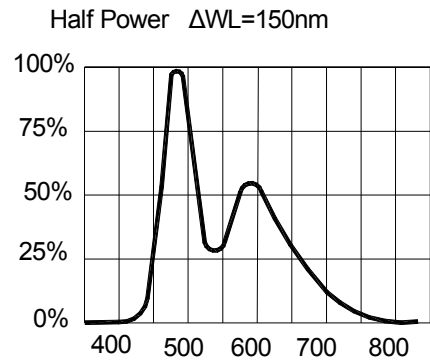
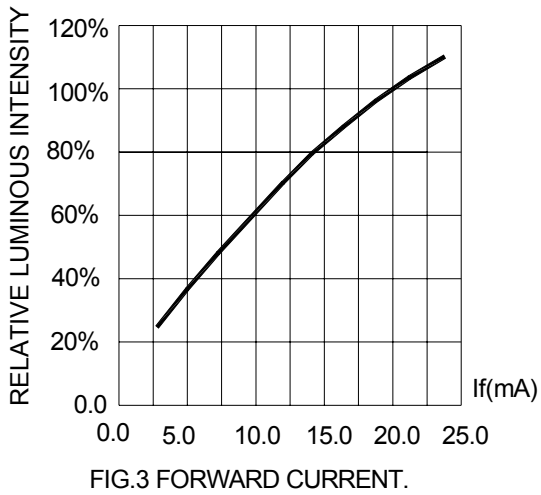
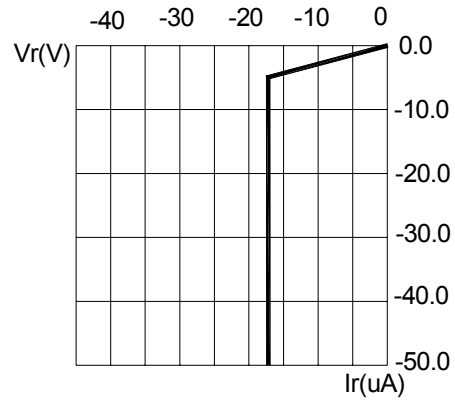
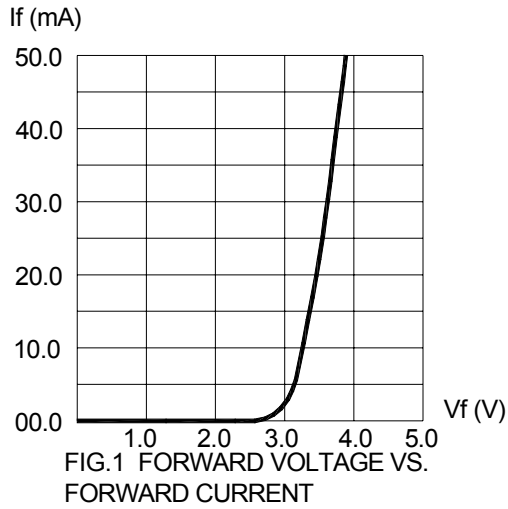
Color Bin Table (IF=20mA):



WN	X1	Y1	X2	Y2	X3	Y3	X4	Y4
B	0.283	0.305	0.3223	0.3523	0.324	0.311	0.296	0.276



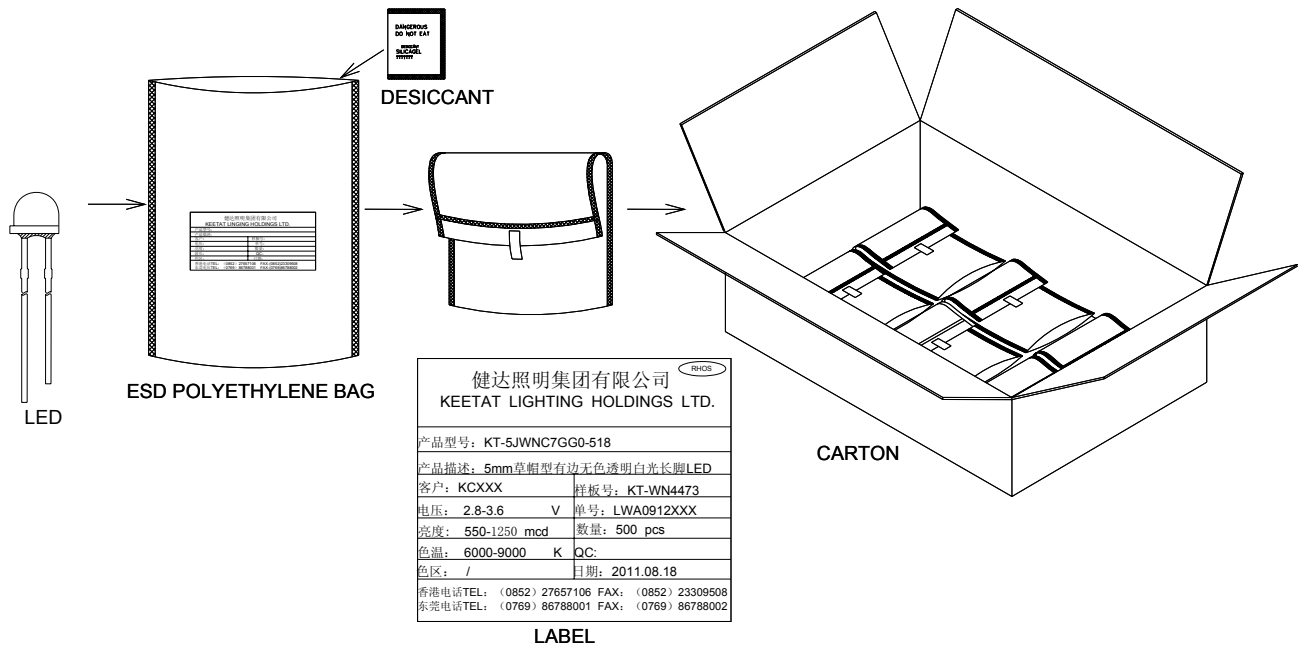
Optical-Electrical Characteristic Graphs



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Packaging Standard:



Important Notes:

- 1) Do not apply any stress to the lead, particularly when heated.
- 2) The LEDs must not be repositioned after soldering.
- 3) After soldering the LEDs, the epoxy bulb should be protected from mechanical shock or vibration until the LEDs return to room temperature.
- 4) Direct soldering onto a PC board should be avoided, Mechanical stress to the resin may be caused by the PC board warping or from the clinching and cutting of the lead frames, When it is absolutely necessary, the LEDs may be mounted in this fashion, but, the User will assume responsibility for any problems, Direct soldering should only be done after testing has confirmed that no damage, such as wire bond failure or resin deterioration, will occur.
- 5) When it is necessary to clamp the LEDs to prevent soldering failure, it is important to minimize the mechanical stress on the LEDs.
- 6) Cut the LED leadframes at room temperature, Cutting the lead frames at high temperatures may cause LED failure.
- 7) Customer acknowledges that it should not operate the samples beyond the level recommended in the specification guidelines.

Item	Signatures	Date	Revision History		
Prepared by	Huai Wang	2011-09-16	Rev. No	Date	Change Description
Checked by	Frank Yan	2011-09-16			
Approved by	Bill Zhang	2011-09-16			
FCN#					

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